L Number	Hits	Search Text	DB	Time stamp
1	2175	Via near15 contact$3 near15 (through or thru) near15 (chip or wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:12
2	5920	(slop$3 or taper$3) near5 via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:13
3	130796	(front or top) near10 (wafer or substrate or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:15
4	127681	(back or bottom) near10 (wafer or substrate or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:16
5	36968	((front or top) near10 (wafer or substrate or chip)) same ((back or bottom) near10 (wafer or substrate or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:16
6	39	(Via near15 contact$3 near15 (through or thru) near15 (chip or wafer or substrate)) and ((slop$3 or taper$3) near5 via) and (((front or top) near10 (wafer or substrate or chip)) same ((back or bottom) near10 (wafer or substrate or chip)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:16

L Number	Hits	Search Text	DB	Time stamp
1	2175	Via near15 contact$3 near15 (through or thru) near15 (chip or wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:12
2	5920	(slop$3 or taper$3) near5 via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:13
3	130796	(front or top) near10 (wafer or substrate or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:15
4	127681	(back or bottom) near10 (wafer or substrate or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:16
5	36968	((front or top) near10 (wafer or substrate or chip)) same ((back or bottom) near10 (wafer or substrate or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:16
6	39	(Via near15 contact$3 near15 (through or thru) near15 (chip or wafer or substrate)) and ((slop$3 or taper$3) near5 via) and (((front or top) near10 (wafer or substrate or chip)) same ((back or bottom) near10 (wafer or substrate or chip)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:37
7	817	(contact$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:38
8	12848	contact near15 ((front or top) near10 (wafer or substrate or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:39
9	262	((contact$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:39
10	0	(((contact$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))) and ((slop$3 or taper$3) near5 via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:40
11	54	(((contact$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))) and (Via near15 contact$3 near15 (through or thru) near15 (chip or wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:40
12	8	((((contact$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))) and (Via near15 contact$3 near15 (through or thru) near15 (chip or wafer or substrate))) and (slop$3 or taper$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:43

13	32	((((contact$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))) and (Via near15 contact$3 near15 (through or thru) near15 (chip or wafer or substrate))) and (via adj5 contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:43